

**What is claimed is:**

1. A leadframe to be used in a semiconductor device,  
which comprises a plurality of parallel first  
leads and a plurality of parallel second leads,  
wherein the pitch of the first leads is different  
from that of the second leads, and the first leads  
are joined end-to-end with the second leads.
2. The leadframe according to claim 1,  
wherein at least either of the first leads or the  
second leads have their thickness reduced.
3. A method for manufacturing a semiconductor device  
using a leadframe,  
which comprises the steps of mounting a semi-  
conductor element on the leadframe according to claim  
1, and encapsulating the semiconductor element in  
a package,  
wherein the dimension of the package for en-  
capsulation is set such that at least either of the  
first leads or the second leads project from the  
package.
4. The method for manufacturing a semiconductor device  
using a leadframe, according to claim 3,

wherein at least either of the first leads or the second leads are squeezed by a mold for molding the package and have their thickness reduced.

5. A semiconductor device using the leadframe according to claim 1.
6. An electronic equipment using the semiconductor device according to claim 5.